

Plating Process

Plating Equipment
for Semiconductor Panel Level Packaging

Technical Specifications

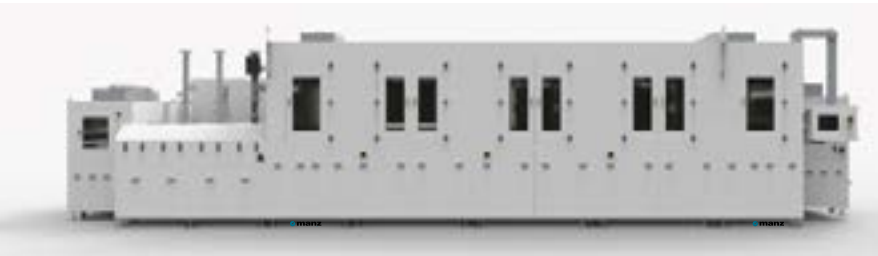
Plating Equipment

| | |
|-----------------------------------|---|
| Panel Size (mm) | 300/ 500/ 600/ 700 |
| Anode | Insoluble/ Multiple Zone |
| Convection/Agitation | Paddle Type & Fan Type |
| Membrane | Ionic Exchange Membrane |
| Warpage allowance | Max. ≤10 mm |
| Cathode Contact Failure Detection | Yes |
| Blanket uniformity | > 95% |
| Application | RDL Trace & Via Filling Copper Bump & Pillar Plating Stud & Heat Sink Plating |
| Type of carrier substrate | Stainless, Epoxy, Glass & CCL (FR-4) |

Description

| | |
|--------------|--|
| Process flow | Loading→Micro Etch→Acid Rinse→Cu Plating→Water Rinse→Dry→Unloading |
|--------------|--|

*Specific performance parameters depend on the application.



Features

- **Hassle-Free Operation**
Jig-free design for easy handling, less maintenance, and maximum uptime.
- **Scalable & Flexible**
Modular design expands with your needs and simplifies maintenance.
- **Superior Plating Quality**
Multi-anode system delivers >95% uniformity and minimizes edge effects.
- **High-Performance Capability**
Achieves copper thickness beyond 150 μm with >15 ASD for advanced applications.
- **Smart CMS Integration**
Inline chemical monitoring with automatic dosing for stable process control.

